

IN THE CLAIMS:

1. (Original) An electronic component characterized by its structure wherein a heat
conductive adhesive made by blending boron nitride powder that has a diamagnetic an-isotropic
magnetic susceptibility and adhesive polymer is interposed between a heating device and a heat
conductive member, and adhering with boron nitride powder oriented in the heat conductive
5 adhesive to a fixed direction under a magnetic field atmosphere by the use of the diamagnetic
an-isotropic magnetic susceptibility of the boron nitride powder.

2. (New) An electronic component according to claim 1, wherein the boron nitride
powder is a boron nitride powder of hexagonal system or cubic system.

3. (New) An electronic component according to claim 1, wherein the boron nitride
powder is aligned in the gap direction of objects to be adhered, namely, in the adhesive
thickness direction.

4. (New) An electronic component, comprising:

a heat generating part;

a heat conductive part; and

a heat conductive adhesive made by blending boron nitride powder that has a
5 diamagnetic an-isotropic magnetic susceptibility and an adhesive polymer, said heat conductive
adhesive being interposed between said heat generating part and said heat conductive part and

being adhered to each of said heat generating part and said heat conductive part, said boron nitride powder being oriented in a fixed direction in said heat conductive adhesive with said fixed direction being attained by subjecting said heat conductive adhesive to a magnetic field
10 prior to setting or during setting of the adhesive with the fixed direction being due to the diamagnetic an-isotropic magnetic susceptibility of the boron nitride powder.

5. (New) An electronic component according to claim 4, wherein the boron nitride powder is a boron nitride powder of hexagonal system or cubic system.

6. (New) An electronic component according to claim 4, wherein a distance between said heat generating part and said heat conductive part defines adhesive thickness and the boron nitride powder is aligned in a direction of said adhesive thickness.

7. (New) An electronic component, comprising:

a heat generating part;

a heat conductive part; and

a heat conductive adhesive made by blending boron nitride powder that has a
5 diamagnetic an-isotropic magnetic susceptibility and an adhesive polymer, said heat conductive adhesive being interposed between a surface of said heat generating part and a surface of said heat conductive part and being adhered to each of said heat generating part and said heat conductive part, said boron nitride powder including boron nitride with a flake shape having a

small thickness and a large length, said boron nitride powder being oriented in a fixed direction
10 in said heat conductive adhesive including boron nitride with a flake shape having the length
substantially perpendicular to each of said surface of said heat generating part and said surface
of said heat conductive part with said fixed direction being attained by subjecting said heat
conductive adhesive to a magnetic field prior to setting or during setting of said adhesive with
the fixed direction being due to the diamagnetic an-isotropic magnetic susceptibility of the
15 boron nitride powder.

8. (New) An electronic component according to claim 7, wherein the boron nitride
powder is a boron nitride powder of hexagonal system or cubic system.